

PACKAGE

30 CLK

SCES126H-FEBRUARY 1998-REVISED SEPTEMBER 2004

FEATURES	DGG, DGV, OR	
<ul> <li>Member of the Texas Instruments Widebus™ Family</li> </ul>	, ,	
Operates From 1.65 V to 3.6 V		56 GND
<ul> <li>Max t<sub>pd</sub> of 2 ns at 3.3 V</li> </ul>	NC 2	55 🛛 NC
• ±12-mA Output Drive at 3.3 V	Y1 3	54 A1
<ul> <li>Ideal for Use in PC100 Register DIMM, Revision 1.1</li> </ul>	GND	53 GND 52 A2 51 A3
<ul> <li>Output Port Has Equivalent 26-Ω Series</li> </ul>		50 V <sub>CC</sub>
Resistors, So No External Resistors Are	Y4 🛛 8	49 A4
Required	Y5 9	48 A5
Latch-Up Performance Exceeds 250 mA Per	Y6 🛛 10	47 🛛 A6
JESD 17	GND 🚺 11	46 GND
ESD Protection Exceeds JESD 22	Y7 🛛 12	45 🛛 A7
– 2000-V Human-Body Model (A114-A)	Y8 🛛 13	44 🛛 A8
– 200-V Machine Model (A115-A)	Y9 🛛 14	43 A9
– 1000-V Charged-Device Model (C101)	Y10 15	42 A10
	Y11 16 Y12 17	41 A11
DESCRIPTION/ORDERING INFORMATION	GND 18	40   A12 39   GND
This 18-bit universal bus driver is designed for 1.65-V	Y13 19	38 A13
to $3.6-V V_{CC}$ operation.	Y14 20	37 A14
	Y15 21	36 A15
Data flow from A to Y is controlled by the output-enable $(\overline{OE})$ input. The device operates in the	V <sub>CC</sub> [ 22	35 🛛 V <sub>CC</sub>
transparent mode when the latch-enable (LE) input is	Y16 23	34 🛛 A16
high. When LE is low, the A data is latched if the	Y17 🚺 24	33 🛛 A17
clock (CLK) input is held at a high or low logic level. If	GND 🛛 25	32 GND
LE is low, the A data is stored in the latch/flip-flop on	Y18 🛛 26	31 🛛 A18

NC - No internal connection

29 GND

OE 27

LE

28

#### PACKAGE<sup>(1)</sup> **ORDERABLE PART NUMBER TOP-SIDE MARKING** TA Tube SN74ALVC162835DL SSOP - DL ALVC162835 Tape and reel SN74ALVC162835DLR -40°C to 85°C **TSSOP - DGG** Tape and reel SN74ALVC162835DGGR ALVC162835 **TVSOP - DGV** Tape and reel SN74ALVC162835DGVR VC2835

#### **ORDERING INFORMATION**

Package drawings, standard packing guantities, thermal data, symbolization, and PCB design guidelines are available at (1)www.ti.com/sc/package.



driver.

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the low-to-high transition of CLK. When  $\overline{OE}$  is high,

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>cc</sub> through a

pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the

The output port includes equivalent 26- $\Omega$  series

resistors to reduce overshoot and undershoot.

the outputs are in the high-impedance state.

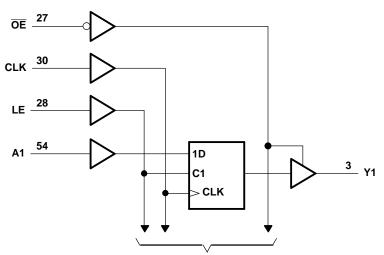
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#### **FUNCTION TABLE**

	IN	PUTS		OUTPUT
OE	LE	CLK	Α	Y
н	Х	Х	Х	Z
L	Н	Х	L	L
L	Н	Х	Н	н
L	L	$\uparrow$	L	L
L	L	$\uparrow$	Н	н
L	L	L or H	Х	Y <sub>0</sub> <sup>(1)</sup>

(1) Output level before the indicated steady-state input conditions were established



### LOGIC DIAGRAM (POSITIVE LOGIC)

To 17 Other Channels

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	4.6	V
VI	Input voltage range <sup>(2)</sup>		-0.5	4.6	V
Vo	Output voltage range <sup>(2)(3)</sup>	Dutput voltage range <sup>(2)(3)</sup>		V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
I <sub>O</sub>	Continuous output current			±50	mA
	Continuous current through each $V_{CC}$ or $G$	SND		±100	mA
		DGG package		64	
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DGV package		48	°C/W
		DL package		56	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This value is limited to 4.6 V maximum.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.



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## **RECOMMENDED OPERATING CONDITIONS**<sup>(1)</sup>

			MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage		1.65	3.6	V	
		$V_{CC} = 1.65 \text{ V} \text{ to } 1.95 \text{ V}$	$0.65  imes V_{CC}$			
VIH	High-level input voltage	$V_{CC}$ = 2.3 V to 2.7 V	1.7		V	
		$V_{CC} = 2.7 V \text{ to } 3.6 V$	2			
		$V_{CC} = 1.65 \text{ V} \text{ to } 1.95 \text{ V}$		$0.35 \times V_{CC}$		
V <sub>IL</sub>	Low-level input voltage	$V_{CC}$ = 2.3 V to 2.7 V		0.7	V	
		$V_{CC} = 2.7 V \text{ to } 3.6 V$		0.8		
VI	Input voltage		0	3.6	V	
Vo	Output voltage		0	V <sub>CC</sub>	V	
		V <sub>CC</sub> = 1.65 V		-2		
	Lich lovel output ourrest	$V_{CC} = 2.3 V$		-6	mA	
I <sub>OH</sub>	High-level output current	$V_{CC} = 2.7 V$		-8		
		$V_{CC} = 3 V$		-12		
		V <sub>CC</sub> = 1.65 V		2		
		V <sub>CC</sub> = 2.3 V		6	~ ^	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		8	mA	
		$V_{CC} = 3 V$		12		
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V	
T <sub>A</sub>	Operating free-air temperature		-40	85	°C	

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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#### **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup> MAX	
	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2		
	I <sub>OH</sub> = -2 mA	1.65 V	1.2		
	I <sub>OH</sub> = -4 mA	2.3 V	1.9		
V <sub>OH</sub>		2.3 V	1.7		V
	I <sub>OH</sub> = -6 mA	3 V	2.4		
	I <sub>OH</sub> = -8 mA	2.7 V	2		
	I <sub>OH</sub> = -12 mA	3 V	2		
	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V		0.1	2
	I <sub>OL</sub> = 2 mA	1.65 V		0.4	5
	I <sub>OL</sub> = 4 mA	2.3 V		0	1
V <sub>OL</sub>	$I_{OL} = 6 \text{ mA}$	2.3 V		0.5	5 V
		3 V		0.5	5
	I <sub>OL</sub> = 8 mA	2.7 V		0.	6
	I <sub>OL</sub> = 12 mA	3 V		0.	3
I <sub>I</sub>	$V_1 = V_{CC}$ or GND	3.6 V		±:	5 μΑ
I <sub>OZ</sub>	$V_{O} = V_{CC}$ or GND	3.6 V		±1	) μΑ
I <sub>CC</sub>	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	3.6 V		4	) μΑ
$\Delta I_{CC}$	One input at $V_{CC}$ - 0.6 V, Other inputs at $V_{CC}$ or GND	3 V to 3.6 V		75	) μΑ
Ci Control inputs	V = V or CND	3.3 V	3.5		рF
Data inputs	$V_{I} = V_{CC}$ or GND	3.3 V		рг	
C <sub>o</sub> Outputs	$V_{O} = V_{CC}$ or GND	3.3 V		7	pF

(1) All typical values are at V<sub>CC</sub> = 3.3 V,  $T_A = 25^{\circ}C$ .

## TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				V <sub>CC</sub> =	V <sub>CC</sub> = 1.8 V		$V_{CC}$ = 2.5 V ± 0.2 V		2.7 V	$V_{CC}$ = 3.3 V ± 0.3 V		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f <sub>clock</sub>	Clock frequency				(1)		150		150		150	MHz	
	Dulas duration	LE high		(1)		3.3		3.3		3.3		ns	
t <sub>w</sub>	Pulse duration	CLK high or low		(1)		3.3		3.3		3.3			
		Data before CLK↑		(1)		2.2		2.1		1.7			
t <sub>su</sub>	Setup time		CLK high	(1)		1.9		1.6		1.5		ns	
		Data before LE	CLK low	(1)		1.3		1.1		1			
the state of the s		Data after CLK↑		(1)		0.6		0.6		0.7		ns	
t <sub>h</sub>	Hold time	Data after LE $\downarrow$	CLK high or low	(1)		1.4		1.7		1.4			

(1) This information was not available at the time of publication.



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## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	(OUTPUT)	_		1.8 V	V <sub>CC</sub> = ± 0.	2.5 V 2 V	V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = ± 0.	3.3 V 3 V	UNIT
	(INPUT)		MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX		
f <sub>max</sub>			(1)		150		150		150		MHz	
	A			(1)	1	5		5	1	4.2		
t <sub>pd</sub>	LE	Y		(1)	1.3	5.9		5.8	1.3	5.1	ns	
	CLK			(1)	1.4	6.3		6.1	1.4	5.4		
t <sub>en</sub>	OE	Y		(1)	1.4	6.3		6.5	1.1	5.5	ns	
t <sub>dis</sub>	OE	Y		(1)	1	4.9		4.9	1.3	4.5	ns	

(1) This information was not available at the time of publication.

### SWITCHING CHARACTERISTICS

from 0°C to 85°C,  $C_L = 0 \text{ pF}$ 

PARAMETER	ARAMETER FROM TO (INPUT) (OUTPUT)		V <sub>CC</sub> = 3. ± 0.15	UNIT	
	(INPOT)	(001-01)	MIN	MAX	
+ (1)	A	X	0.9	2	~~
t <sub>pd</sub> <sup>(1)</sup>	CLK	Ŷ	1.4	2.9	ns

(1) Texas Instruments SPICE simulation data

### SWITCHING CHARACTERISTICS

from 0°C to 65°C,  $C_L = 50 \text{ pF}$ 

PARAMETER	FROM	TO	V <sub>CC</sub> = 3. ± 0.15	$V_{CC}$ = 3.3 V ± 0.15 V		
	(INPUT)	(OUTPUT)		MAX		
	A	Y	1	4		
Lpd	CLK	Ť	1.9	5	ns	

## **OPERATING CHARACTERISTICS**

 $T_A = 25^{\circ}C$ 

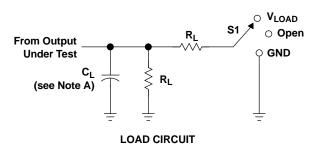
	PARAMETER		TEST (	CONDITIONS	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	UNIT
C	Power dissipation	Outputs enabled	$C_1 = 0.$	f = 10 MHz	(1)	35.5	40	۶F
C <sub>pd</sub>	capacitance	Outputs disabled	$C_{L} = 0,$		(1)	12.5	14	μr

(1) This information was not available at the time of publication.



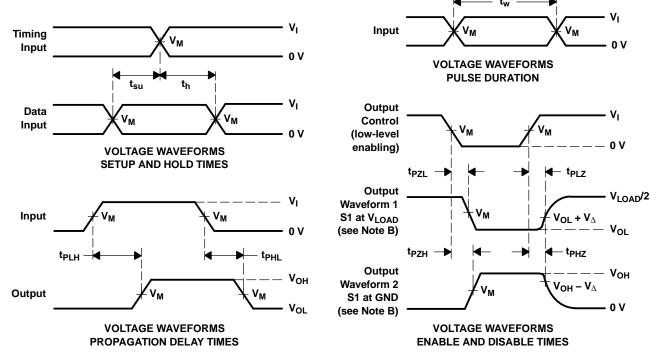
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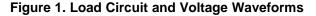
TEST	S1
t <sub>pd</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

Γ	V			v	6	Р	v	
	V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	RL	$V_{\Delta}$
ſ	1.8 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	$2 \times V_{CC}$	30 pF	<b>1 k</b> Ω	0.15 V
	2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	$2 \times V_{CC}$	30 pF	<b>500</b> Ω	0.15 V
	2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V
	3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V

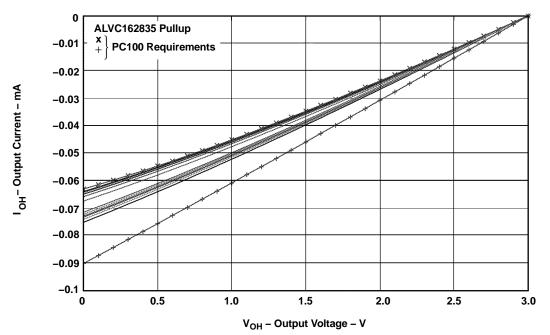


NOTES: A. CL includes probe and jig capacitance.

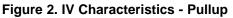
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

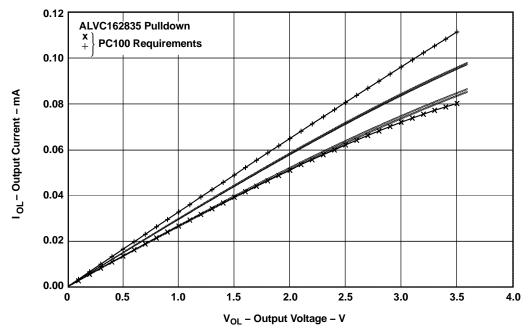


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## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ALVC162835DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVC162835DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVC162835DGVRE4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVC162835DGVRG4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVC162835DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVC162835DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVC162835DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVC162835DGVR	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVC162835DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVC162835DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVC162835DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ALVC162835DGVR	TVSOP	DGV	56	2000	330.0	24.4	6.8	11.7	1.6	12.0	24.0	Q1
SN74ALVC162835DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1



# PACKAGE MATERIALS INFORMATION

11-Mar-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVC162835DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74ALVC162835DGVR	TVSOP	DGV	56	2000	346.0	346.0	41.0
SN74ALVC162835DLR	SSOP	DL	56	1000	346.0	346.0	49.0

# **MECHANICAL DATA**

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

#### DGG (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

**48 PINS SHOWN** 



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



# **MECHANICAL DATA**

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

#### PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G\*\*)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



# **MECHANICAL DATA**

PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

## DGV (R-PDSO-G\*\*)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



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